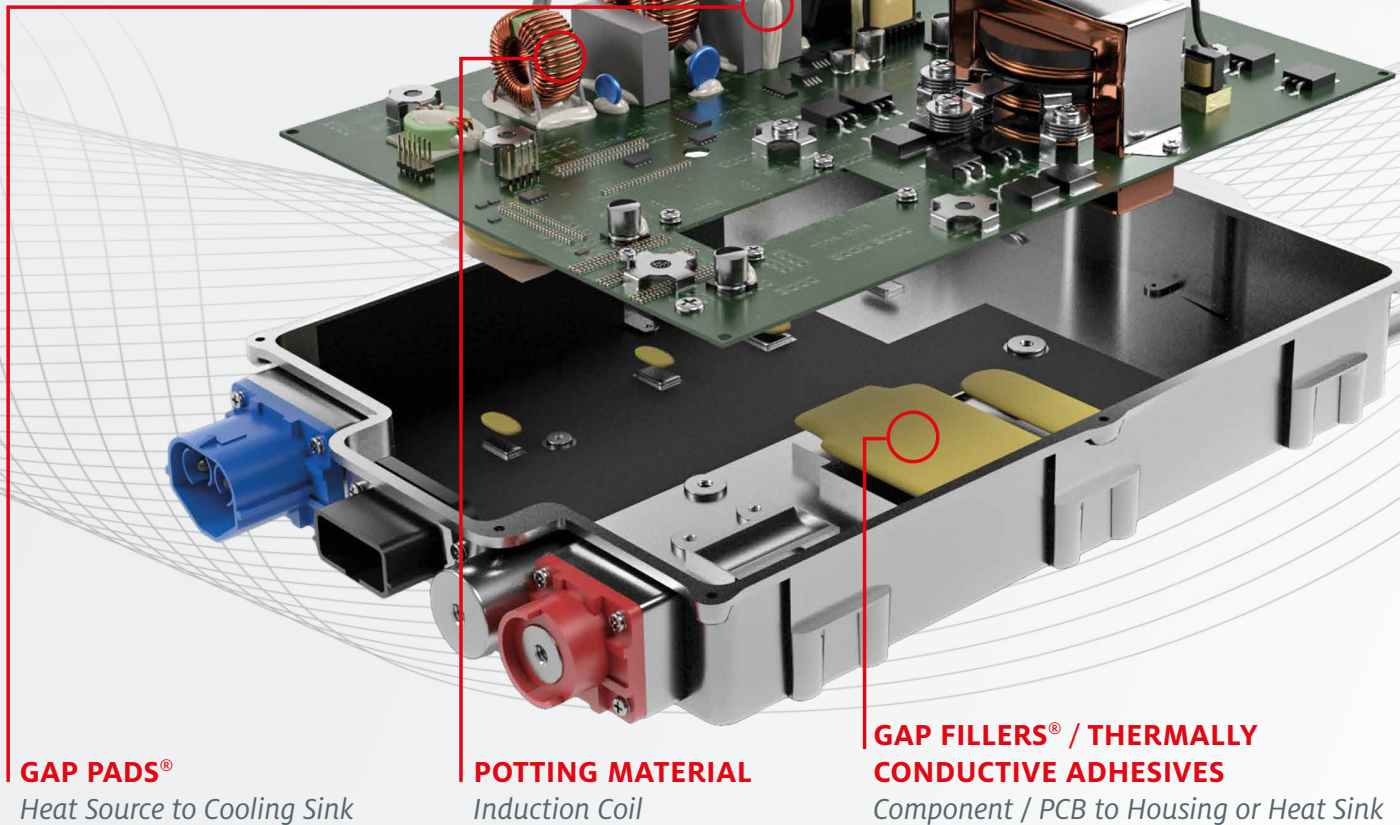


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www.henkel-adhesives.com/emobility



GAP PADS®

Heat Source to Cooling Sink

POTTING MATERIAL

Induction Coil

GAP FILLERS® / THERMALLY CONDUCTIVE ADHESIVES

Component / PCB to Housing or Heat Sink

Henkel Thermal Interface Solutions for EV Power Conversion Systems

Our broad solution portfolio has been specifically designed with a focus on:



System Cost

- » Short cycle times
- » Automated production process



Safety & Reliability

- » Thermal management
- » Oil / ATF resistance



Lifetime Performance

- » Shock and vibration stability
- » Harsh environmental resistance



Vehicle Integration

- » Smaller size higher packing density
- » Consolidation OBC / inverter

Driving e-Mobility, together.



Henkel Thermal Interface Solutions for EV Power Conversion Systems

GAP FILLER®

Product	Chemistry	Curing	Thermal conductivity	Key properties
BERGQUIST TGF 1500	Silicone	RTV or heat	1.8 W/mK	» Low siloxane volatility » High temperature resistance
BERGQUIST TGF 3500LV	Silicone	RTV or heat	3.6 W/mK	» Low Young's Modulus » High dielectric isolation
BERGQUIST TGF 7000	Silicone	RTV or heat	7.0 W/mK	» Highest thermal conductivity » Controlled volatility

GAP PAD®

Product	Thermal conductivity	Dielectric break-down voltage	Hardness / Young's modulus	Key properties
BERGQUIST TGP 1000VOUS	1.0 W/mK	6,000 V at 0.5 mm	Shore 00 = 5/YM = 8 psi	» Ultra soft » Self-tacky one side
BERGQUIST TGP 3000	3.0 W/mK	5,000 V at 0.5 mm	Shore 00 = 15/YM = 16 psi	» High compliant » Low volatility
BERGQUIST TGP HC5000	5.0 W/mK	5,000 V at 0.5 mm	Shore 00 = 35/YM = 17.5 psi	» Highest compliant » Low volatility resin

POTTING MATERIALS

Product	Chemistry	Thermal conductivity	Viscosity (mixed)	Key properties
BERGQUIST TGF 1400SL	Silicone	1.4 W/mK	5,000 mPa·s	» Self leveling » Low volatility
LOCTITE SI 5631 ²	Silicone	1.0 W/mK	5,000 mPa·s	» Excellent cavity filling » Flexible & robust
LOCTITE EA 9496 ¹	Epoxy	1.7 W/mK	15,000 – 40,000 mPa·s	» RTV and warm cure » Low shrinkage
SONDERHOFF FERMADUR SERIES	Polyurethane	0.2 – 0.9 W/mK	500 – 200,000 mPa·s	» RTV and warm cure » Customizable » UL94 V-0 Flame Retardancy » Multi-substrate adhesion

THERMALLY CONDUCTIVE ADHESIVES

Product	Chemistry	Curing	Thermal conductivity	Key properties
BERGQUIST TLB SA3500	Silicone	Heat 125 °C 20 min / 150 °C 10 min	3.5 W/mK	» UL94 V-0 Flame Retardancy » Good flexibility
BERGQUIST TLB EA1800	Epoxy	RTV	1.8 W/mK	» UL94 V-0 Flame Retardancy » High strength

No Number: Available globally | 1: Available only in APAC, EU | 2: Available only in APAC

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